

# Towards miniature carbon-nanotube based X-ray sources

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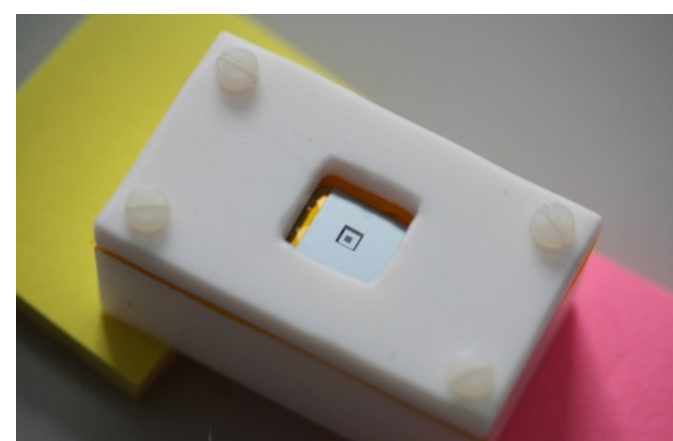
(B) **EMPA** Materials Science & Technology

## Miniature X-ray source concept

### CNTs as field electron emitters

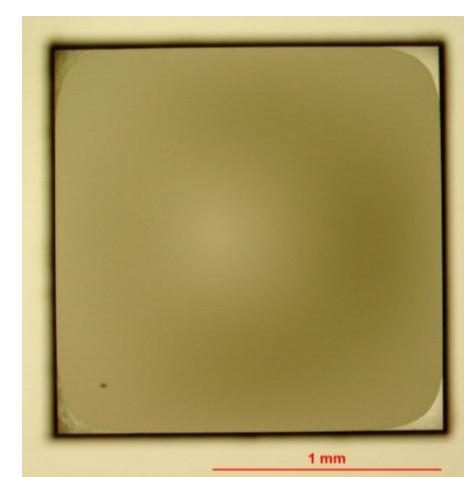
CNT Characteristics:

- Small diameter and high aspect ratio
- Large electrical field enhancement factor and low threshold voltage
- Miniaturization of X-ray source
- Pulsed operation of X-ray source

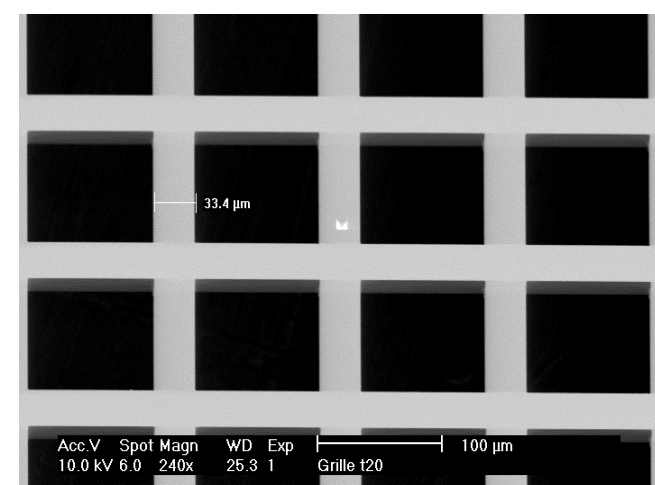


Mock-up of an CNT based miniaturised X-ray source

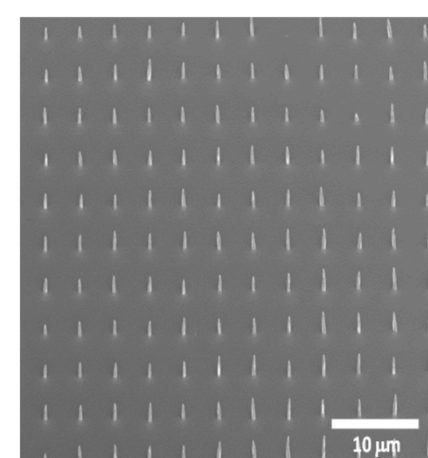
X-ray Diamond Window



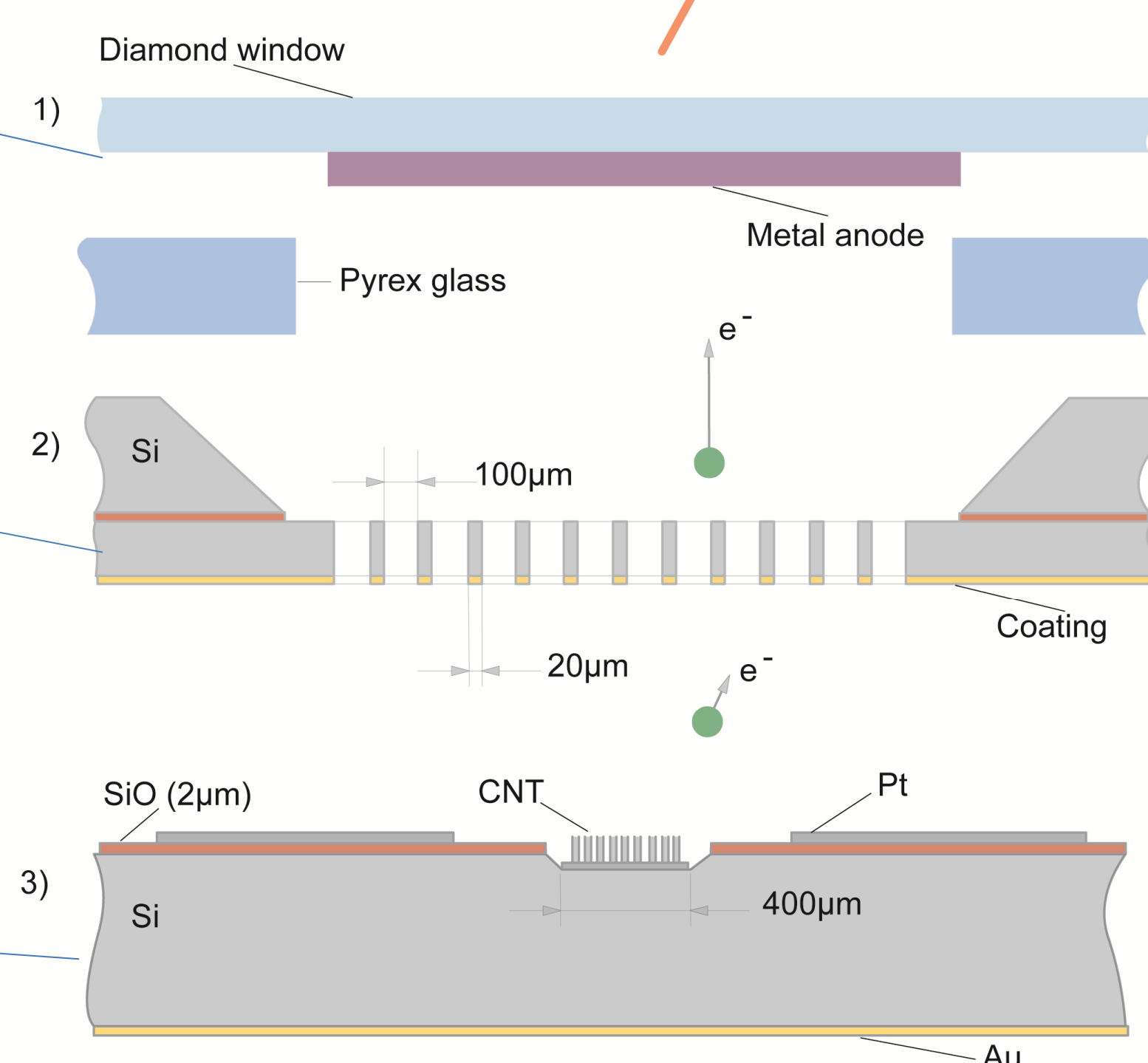
Extraction anode



CNT emission cathode



### X-ray source concept



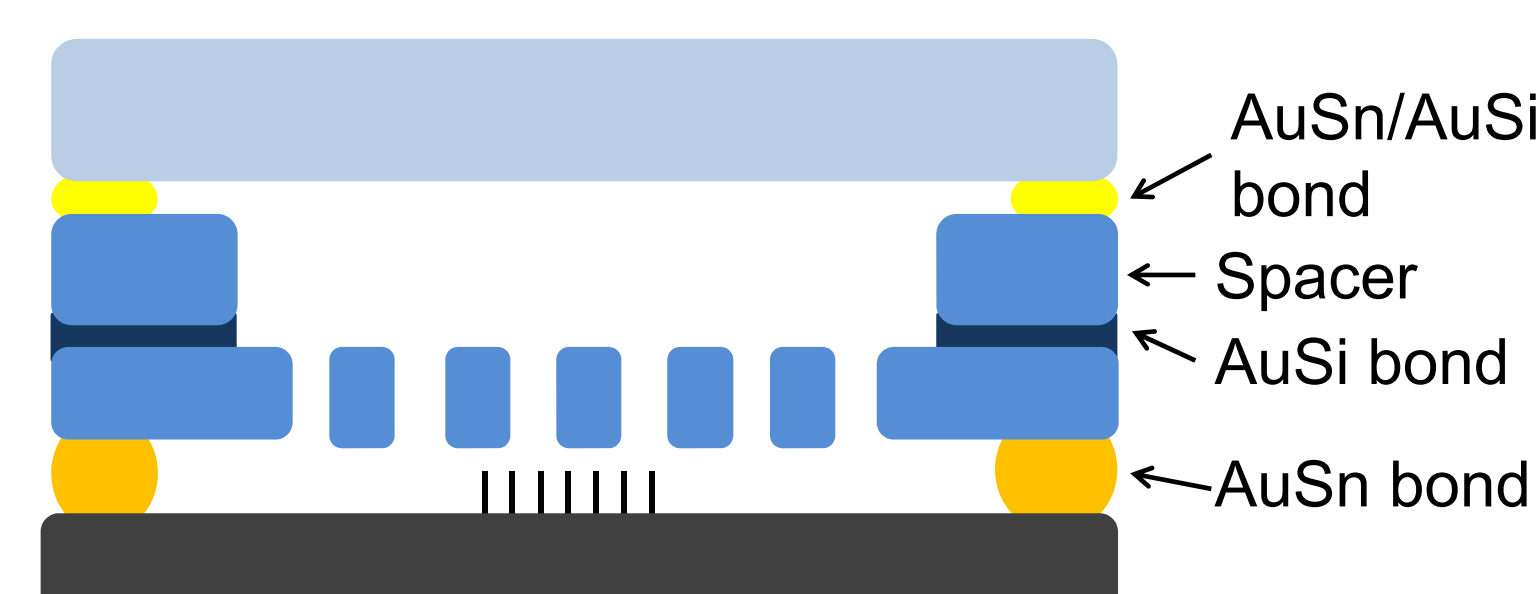
## AuSn Transient Liquid Phase Bonding

### Key requirement for bonding technology

- Hermetic packaging under  $10^{-5}$  mbar for functioning of CNTs
  - Integration of getter material needed
  - Getter activation : 15-30min at 350-450°C in a **sealed cavity**

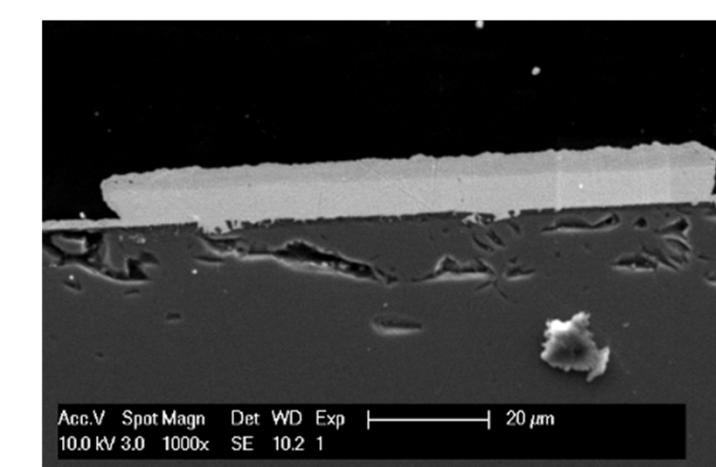
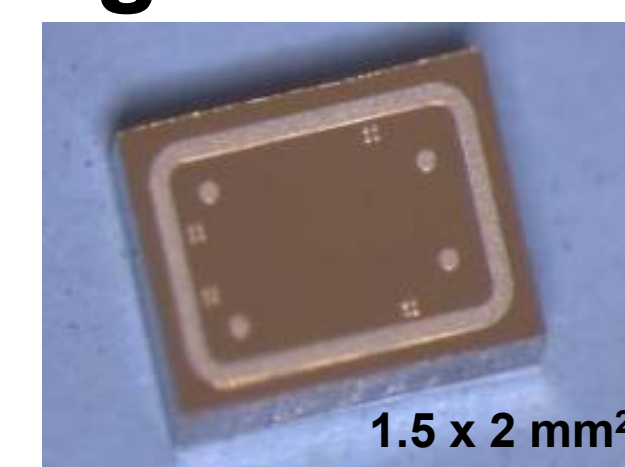
Bonding of CNT wafer and extraction grid based on AuSn TLP process

Au-Sn intermetallic compound formation leading to isothermal solidification at the bonding temperature



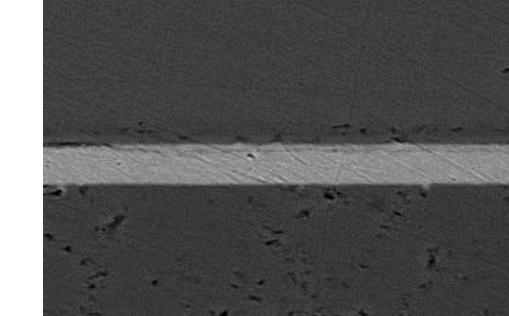
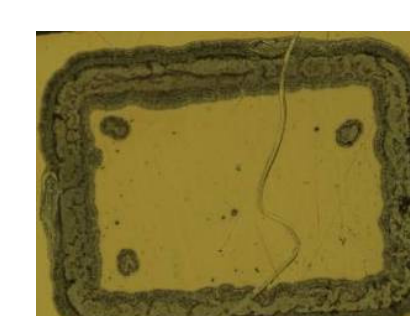
### Solder fabrication and bonding

- Au/Sn multilayer electroplating on thin-film UBM



- Au-rich intermetallic achieved in the whole joint

- 4h annealed samples

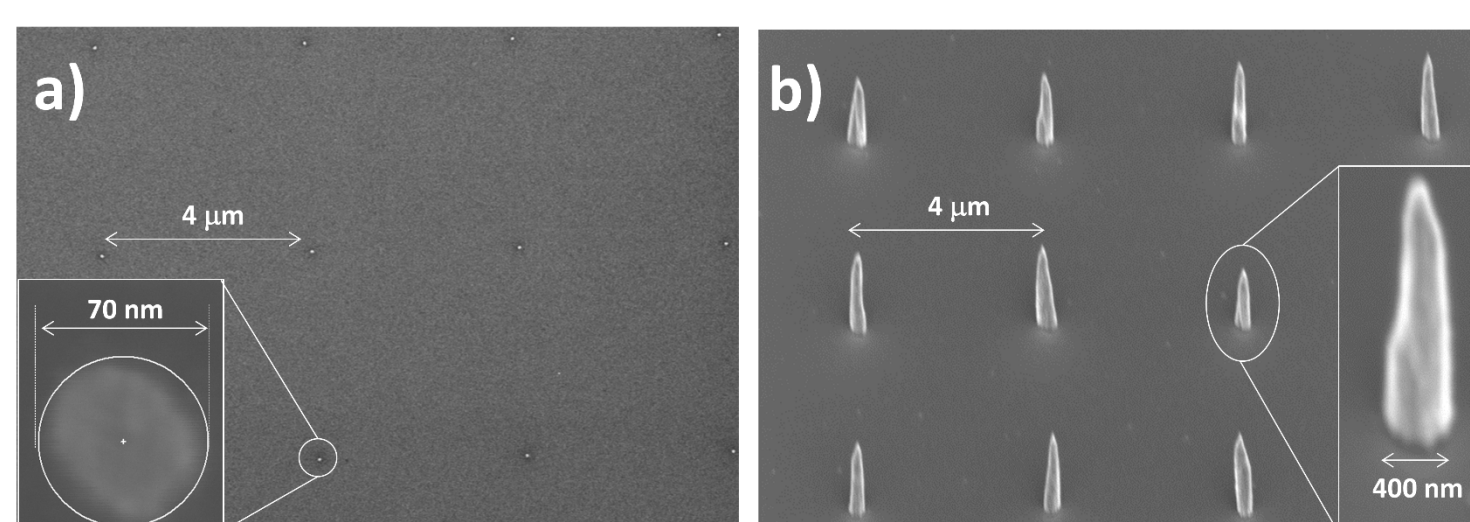


High bonding pressure  
Continuous bonding line

## CNT dies integration and vacuum measurements

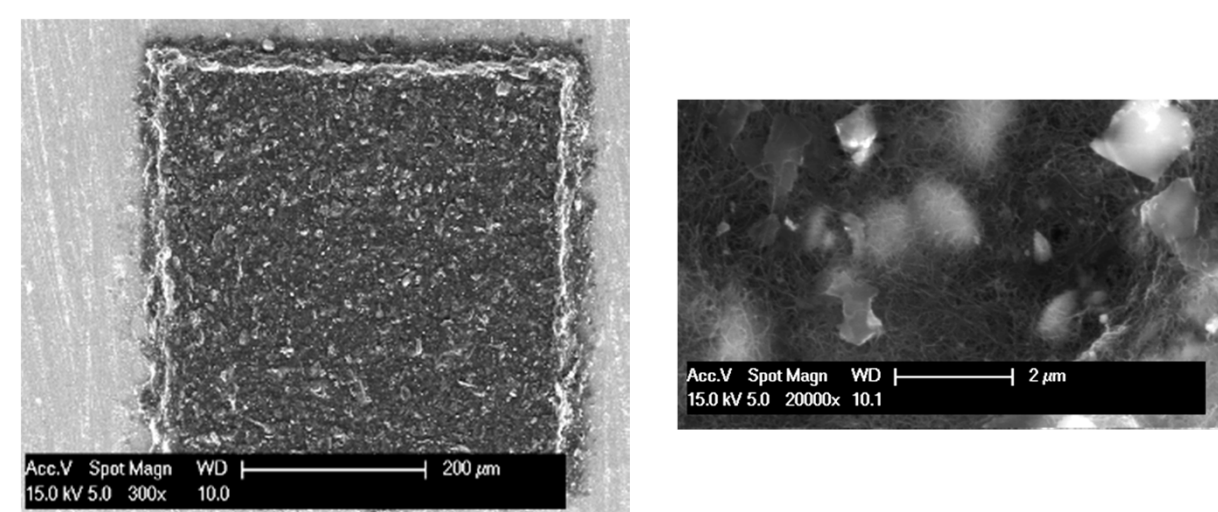
### PECVD growth

- CNTs grown by Plasma Enhanced Chemical Vapour Deposition (PECVD) on Ni nanodots (70 nm diameter)
- E-beam lithography of Ni nanodots arrays on TiN intermediate layer
- High growth temperature of 750°C



### CNT paste technology

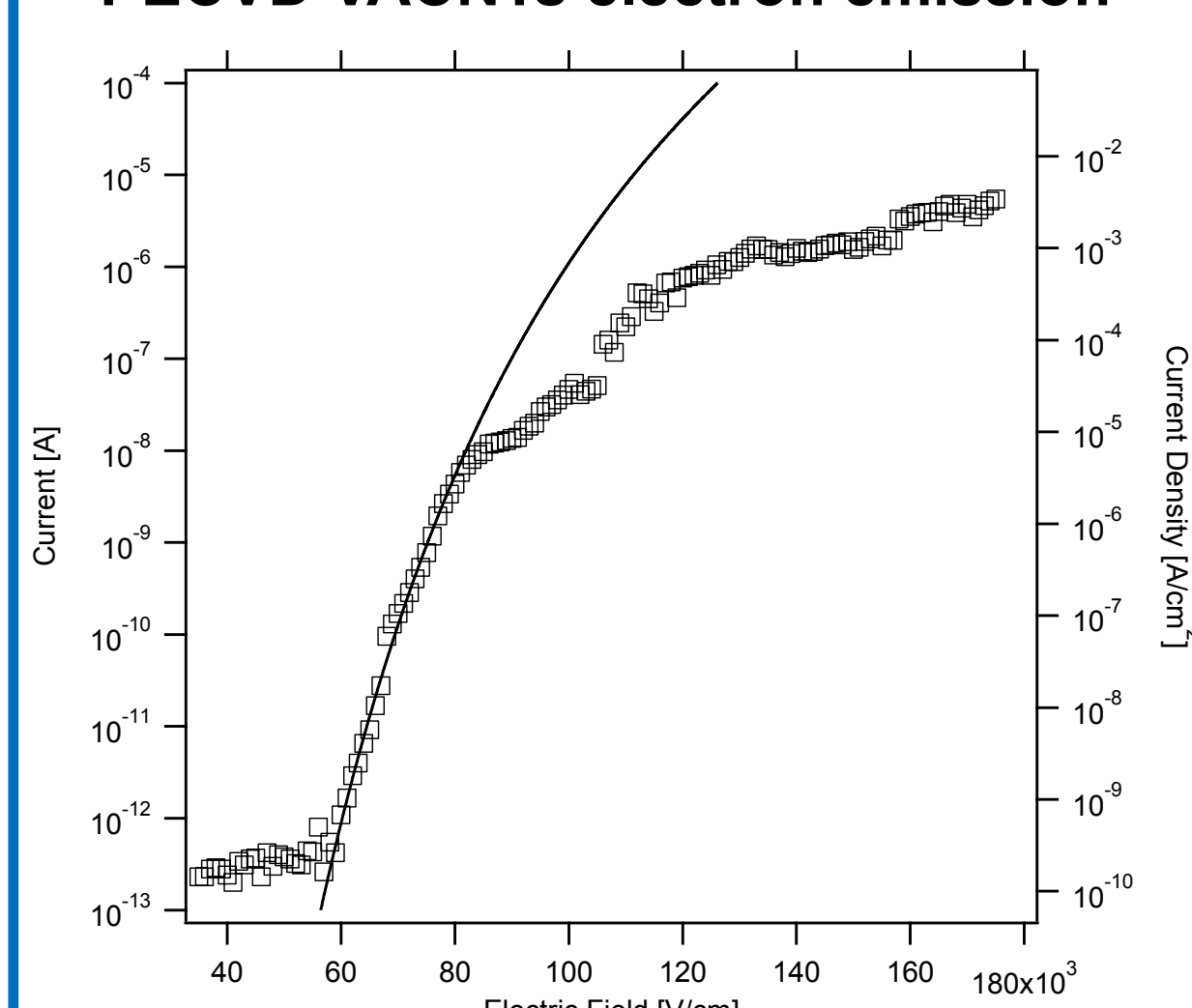
- Screen printing of a carbon nanotube-clay composite paste on molybdenum substrates
- Annealing in vacuum at 880 °C



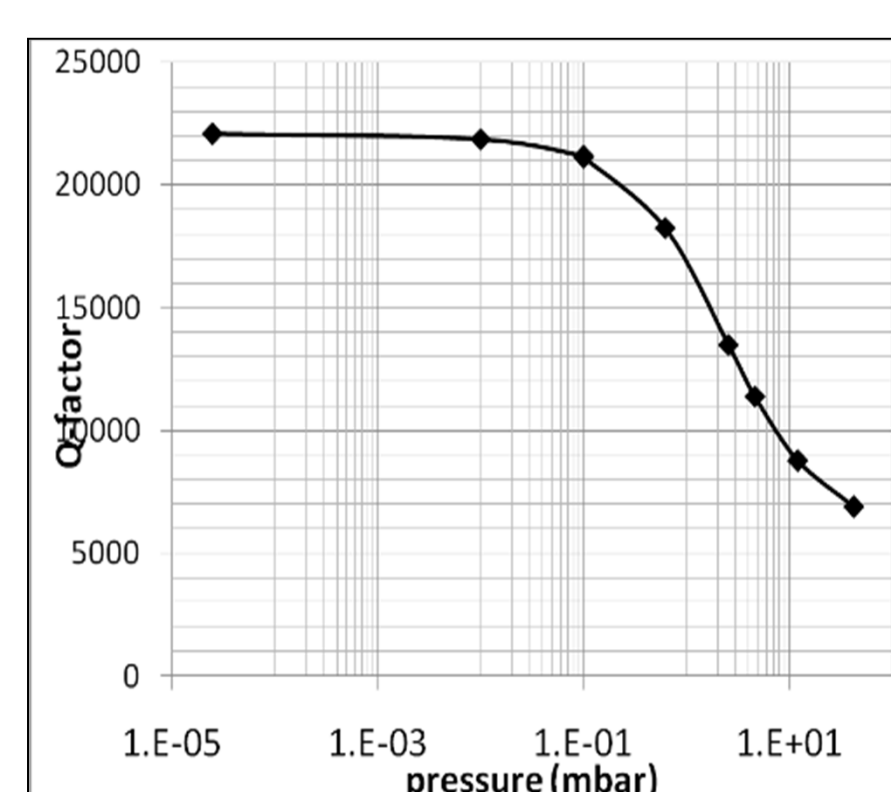
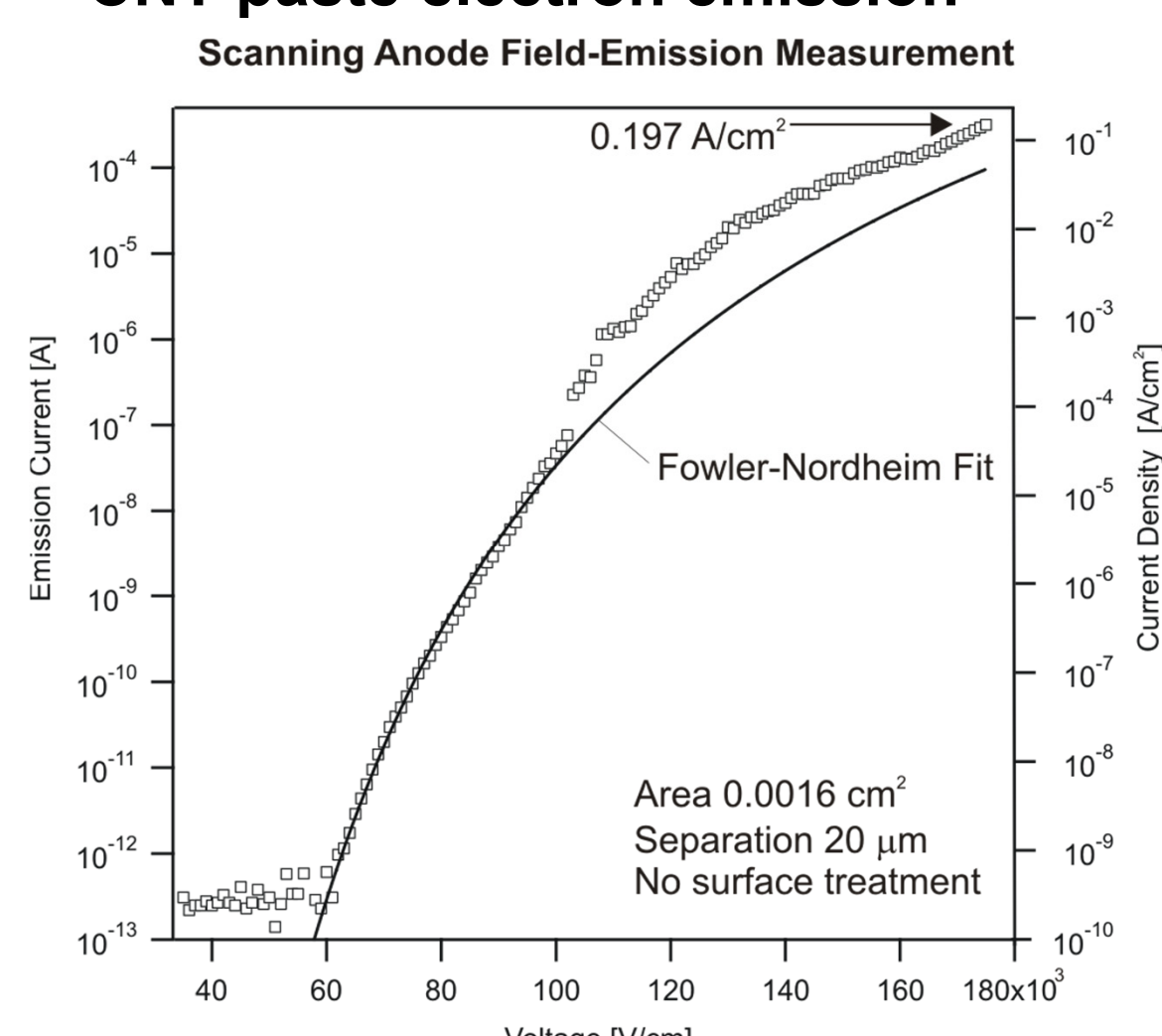
### Electron emission of deposited CNTs

- Repeatable and stable electron emission over a long time (up to several hours) at constant high voltage supply

#### PECVD VACNTs electron emission

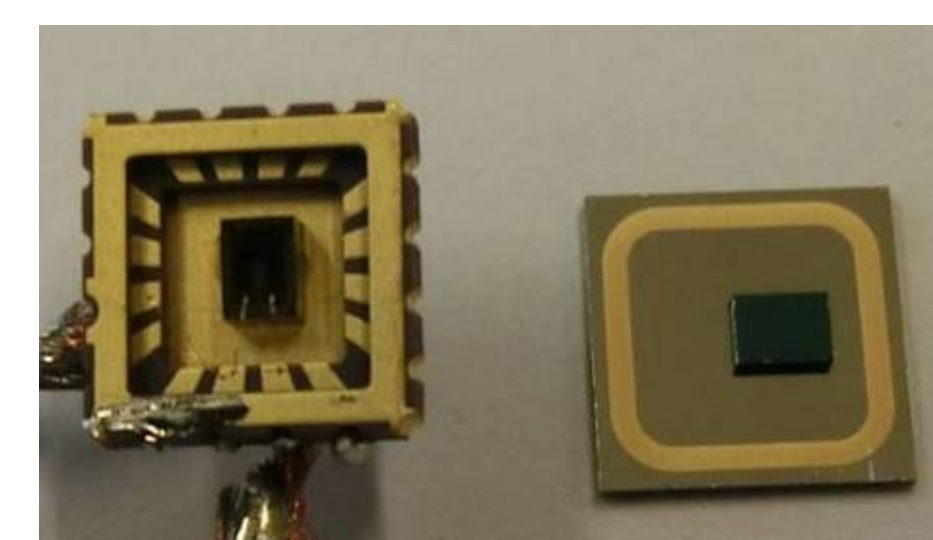


#### CNT paste electron emission



### CNT outgassing experiment

- Harsh deposition conditions of CNTs could affect the outgassing/vacuum level
- CNT dies integrated into ceramic packages and sealed with AuSn eutectic preforms under vacuum (2mbar)
- $\mu$ -resonators used to measure the vacuum level



### Vacuum results

- Q-factors in the range 13'400-13'600 (correspond to ~2mbar)
- No change observed after bonding (15 days)
- No visible difference between packages with CNT dies or without
- No influence of the CNTs on outgassing detected for this vacuum level